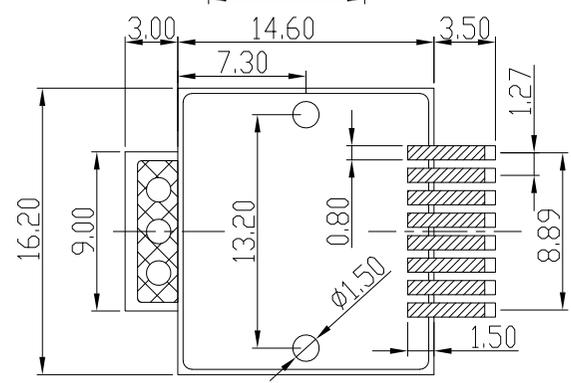
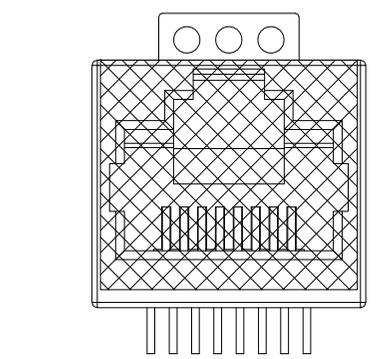
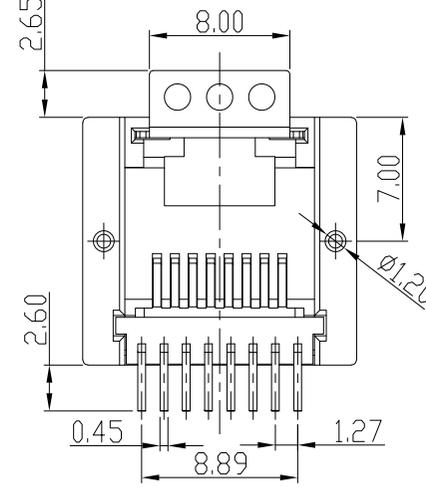
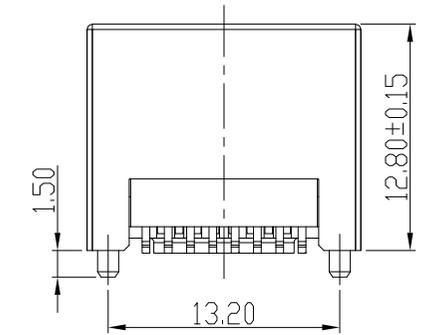
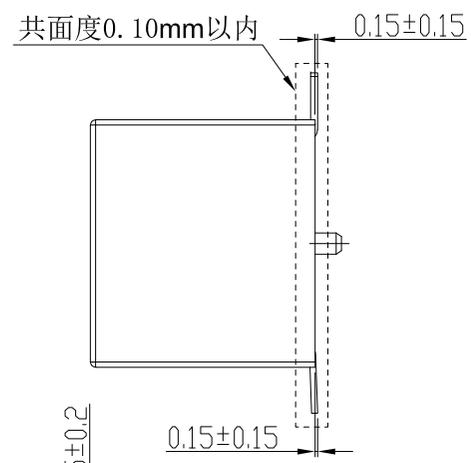
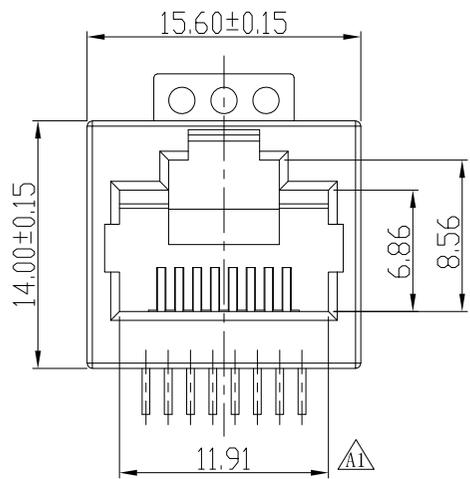


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2016/09/08	Phebe Su
A1			Change dimension	2020/05/21	Hanson



NOTES

MATERIAL

1. HOUSING MATERIAL : LCP BLACK, UL94V-0

2. CONTACT MATERIAL : C5191-H T=0.35mm.

3. PLATING : G/F PLATING OVER NICKEL.

ELECTRICAL

1. VOLTAGE RATING : 125 VAC RMS.

2. CURRENT RATING : 1.5 AMP.

3. CONTACT RESISTANCE : 20 MILLIOHMS MAX.

4. INSULATION RESISTANCE : 1000 MEGOHMS MIN @ 500V DC .

5. DIELECTRIC DIELECTRIC RESISTANCE: 1000V AC RMS 50Hz. 1MIN.

MECHANICAL

1. DURRABILITY : 750 CYCLES MIN.

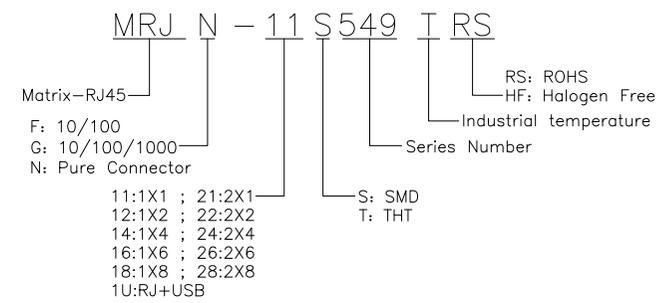
2. PCB RETENTIONPRE-SOLDER : 1 LB MIN.

ENVIRONMENTAL:

1. STORAGE : -40°C~+85°C.

2. OPERATION : -40°C~+85°C.

MATRIX PART NO:



Matrix Electronics Co., Ltd

TOLERANCE: X.X X.XX ±0.25 X.XXX ±0.20 X.XXX ±0.15 ANGLE: ±3°	DESIGN BY : Hanson Huang	DATE : 2020/05/21	PART NAME: RJ45 1x1 JACK W/O LED & SHELL SMD
UNIT: mm [inch]	CHECKED BY: Vicky Hsieh	DATE : 2020/05/21	PART NO. MRJN-11S549TRS
SCALE:1:1 SIZE:A4	APPROVED BY1: Richard Hsieh	DATE : 2020/05/21	MOLD NO. NA
	APPROVED BY2: Richard Hsieh	DATE : 2020/05/21	DRAW NO.
			SHEET NO. 1 OF 1